APA 102-2020-256-8A

- ◆Outline (L* W*H): 2.0*2.0*0.75mm
- Good thermal dissipation & optical uniformity

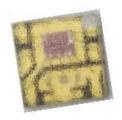


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Features

- RoHS2.0 Compliant
- Packaged in 12mm tape on 7" diameter reels
- EIA STD package
- Compatible with automatic placement equipment and infrared reflow solder process
- Preconditioning: accelerate to JEDEC level 3
- Serial data transmission signal by (DATA CLK) two line

Applications

- Telecommunication, office automation, home appliances, industrial equipment
- Status indicator
- Signal and symbol luminaire
- Front panel backlighting
- Full-color strip.
- Indoor decorative lighting / curtain display

APA- 102 - 2020 - 256 - 8A

1 2

3 4

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1	2	3	4	(5)
Brand Name	Model Number	Lead Frame Size	Gray Scale	Pin Number
Company Prefix	Model: 102	2020: 2.0*2.0mm	256 gray scales	8 Pins type led

■ Maximum Rating(Ta=25°C)

Parameter	Symbol	Rating	Unit		
IC Power Supply Voltage	VDD	-0.4~+5.5	V		
Logic input voltage	VI	-0.4~VDD +0.4	V		
Rate of data signal	Fclk	15	MHZ		
ESD pressure	Vesd	2000	V		
The max led output Current	I _{OMAX}	18	mA		
Soldering Temperature*1	T_{SD}	260	°C		
Operating Temperature Range	-40 Cto+85 C				
Storage Temperature Range		-40 Cto+105 C			

Notes 1: The maximum of soldering time is 5 seconds in T_{SD}

■ Electrical Characteristics (Ta=25° CVDD=5V)

Characteristics	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply voltage	V_{dd}			5.0	5.5	V
Rate of data signal	Fclk			5	-	MHZ
Input high voltage	V _{IH}		$0.7V_{DD}$	=	=	V
Input low voltage	VIL		-	-	0.3V _{DD}	V
The clock high level widch	Тськн		30	-	-	ns
The clock low level widch	T _{CLKL}		30	1	-	ns
Data set up time	TSETUP		10	1	r u	ns
Data hold time	THOLD		5	-	:=	ns
The frequencyof PWM	FPWM			20		KHz
Static power consumpitor	IDD			0.7		mA

■ Optical Characteristics(Ta=25°C;VDD=5V)

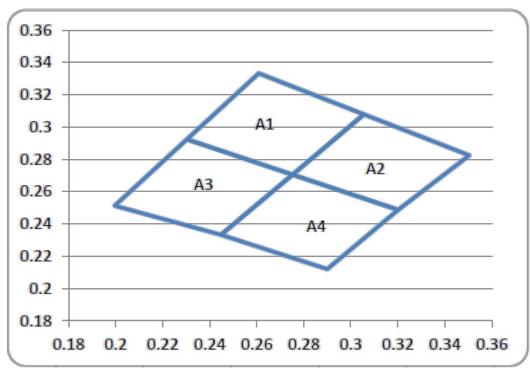
Characteristics	Symbol		Min.	Тур.	Max.	Unit	Test condition	
		R	-	360	:=			
Luminous Intonsity	T _{v v}	G	-	5 10	-	mod	Ι 19πΛ	
Luminous Intensity	Iv	В	-	100	-	mcd	$I_F = 18mA$	
		W	400	800	-			
	λd	R	615	-	630	nm	I _F =18mA	
Dominant Wavelength		G	520	-	535			
		В	460	-	475			
Color Coordinate	Х			0.2752			Ι 10 ο Λ	
Color Coordinate	у			0.275			$I_F=1.8mA$	
View Angle	2θ1,	/2	_	120	-	deg	I _F =18mA	

Range of Bins

1) Luminous Intensity-White($I_F = 18mA$)

Bin Code	Min. IV	Max. IV		
	(mcd)	(mcd)		
P	400	500		
Q	500	630		
R	630	800		
S	800	1000		

■ Color Coordinate Comparison-White



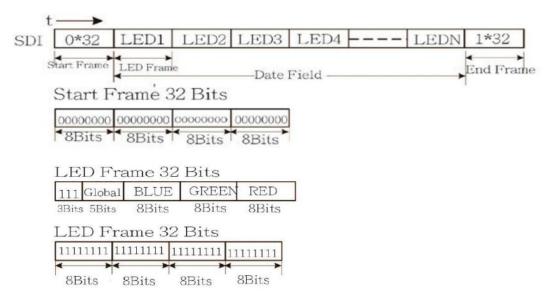
Color Ranks

A1	0. 2609	0. 3332	0. 3056	0. 3078	0. 2752	0. 2705	0. 2303	0. 2923
A2	0. 3056	0. 3078	0. 3504	0. 2824	0. 3202	0. 2487	0. 2752	0. 2705
A3	0. 2303	0. 2923	0. 2752	0. 2705	0. 2448	0. 2332	0. 1996	0. 2513
A4	0. 2752	0. 2705	0. 3202	0. 2487	0. 29	0. 212	0. 2448	0. 2332

Function description

(1) Series data structure

Tandem N-LED

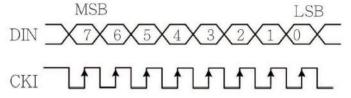


(2) 5-Bit (level 32) brightness adjustment (simultaneous control of OUTR\OUTG\OUTB three port current)

DATA MSB ←→ LSB	Driving Current				
00000	0/31				
00001	1/31				
00010	2/31				

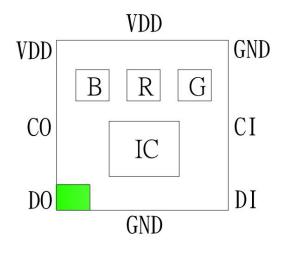
11110	30/31				
11111	31/31(max)				

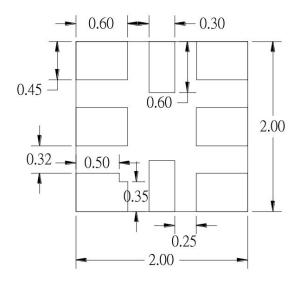
(3) PWM input/output signals relations



Data MSB—	Duty Cycle		
00000000	0/256(min)		
00000001	1/256		
00000010	2/256		
•••			
11111101	253/256		
11111110	254/256		
11111111	255/256(max)		

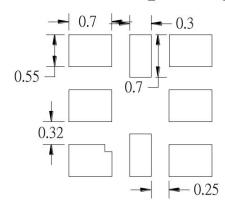
Dimensions



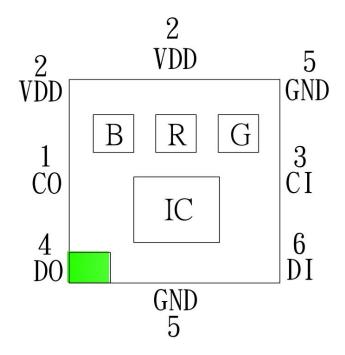




Recommend pad layout



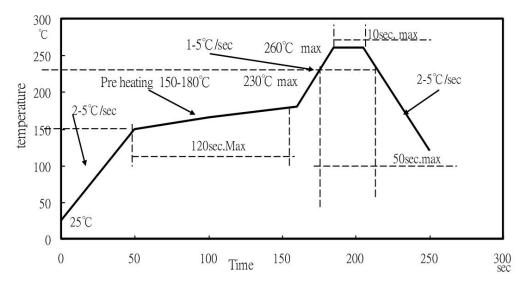
- ☐ All dimensions are in millimeters.
- § Tolerance is ±0.1mm unless other specified
- § Specifications are subject to change without notice



□0.	□ym□ol	□unction description
1	СО	Clock output
2	VDD	supply voltage
3	CI	Clock input
4	DO	Data output
5	GND	Ground
6	DI	Data input

■ Reflow Profile

1. I_R reflow soldering Profilefor Lead Free solder

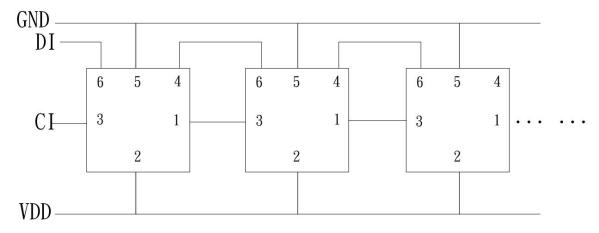


Notes:

- 1. We recommend the reflow temperature at $\mathbb{C}24(\times \mathbb{C})$, and the maximum soldering temperature should be limited to 260
- 2. Don't cause stress to the siliconeresin while it is exposed to high temperature.
- 3. Number of reflow process shall notrbore than time.

■ Test Circuit and Precautions for Use

1. Typical application circuit



2. r a r

2.1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn-out will happen).

2.2. Storage

1). To store the products is recommended with following conditions:

Humidity: 60% R.H. Max.

Temperature: $5^{\circ}\text{C} \sim 30^{\circ}\text{C} (41^{\circ}\text{F} \sim 86^{\circ}\text{F})$

2). Shelf life in sealed bag: 12 month at $< 5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ and < 60% R.H. after the package is Opened, the products should be used within 1 week or they should be keeping to stored at $\leq 20\%$ R.H. with zip-lock sealed.

2.3. Baking

If the package has been opened for more than 1 week, it is recommended to bake the products with the following instruction:

- 1). $60\pm3^{\circ}$ C X 6hrs and <5%RH, for reel
- 2). 125±3°C X 2hrs, for single LED

It shall be normal to see slight color fading of carrier (light yellow) after baking in process

Precautions

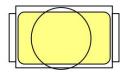
1. Abnormal situation caused by improper setting of collet

To choose the right collet is the key issue in improving the product's quality. LED is different from other electronic components, which is not only about electrical output but also for optical output. This charac made LED more fragile in the process of SMT. If the collet's lowering down height is not well set, it will bring damage to the gold wire at the time of collet's picking up and loading which will cause the LED fail to light up, light up now and then or other quality problems

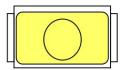
2. How to choose the collet

During SMT, please choose the collet that has larger outer diameter than the lighting area of lens, in a that improper position of collet will damage the gold wire inside the LED. Different collets fit for different products, please refer to the following pictures cross out

Outer diameter of collet should be larger than the lighting area







Picture 2(X)

- 3. Other points for attention
 - A. No pressure should be exerted to the epoxy shell of the SMD under high temperature.
 - B. Do not scratch or wipe the lens since the lens and gold wire inside are rather fragile and cross or easy to break.
 - C. LED should beused as soon as possible who being taken out of thoriginal package, and should be stored in anti-moisture and anti-ESD package.
- 4. This usage and handling instruction is only for your reference

■ Test Items and Results of Reliability

Test Item	Test Conditions	Duration/ Cycle	Ac/Re	Number of Damage	Reference
Normal Temperature Life	$Ta=23^{\circ}C(\pm 5^{\circ}C)$ $I_F=10\text{mA}(5\text{bit-level}$ 15)	1008 hrs	0/1	0/22	JESD22 A-108
High Temperature Life	$Ta=85^{\circ}C(\pm 5^{\circ}C)$ $I_F=10\text{mA}(5\text{bit-level}$ 15)	1008 hrs	0/1	0/22	JESD22 A-108
High Humidity Heat Life	$Ta=85^{\circ}C(\pm 5^{\circ}C)$ $RH=85\%$ $I_{F}=10\text{mA}(5\text{bit-level})$ 15)	1008 hrs	0/1	0/22	JESD22 A-108
Thermal shock	-45°C/30min~105°C /30min (±5°C)	1008 hrs	0/1	0/22	JESD22 A-104
Electrostatic Discharge (ESD) Test	According to the SPEC	3 cycles	0/1	0/22	AEC Q101-001
Low Temperature Storage	T _a =-40°C	1008 hrs	0/1	0/22	JESD22-A103D
High Temperature Storage	T _a =105°C	1008 hrs	0/1	0/22	JESD22-A103D

*Criteria for Judging						
Itom	Condition	Criteria for	Judgment of Pass			
Item	Symbol	Condition	Min	Max		
Luminous Intensity	Iv	I _F =10mA	LSL*2×0.7	J.		

[Note] LSL*2: Lower Specification Level